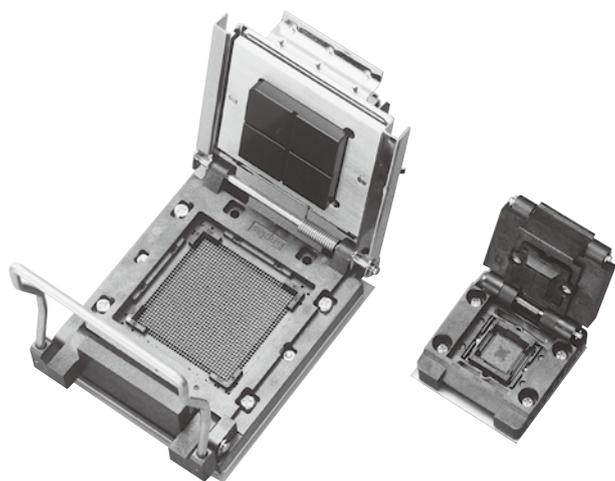


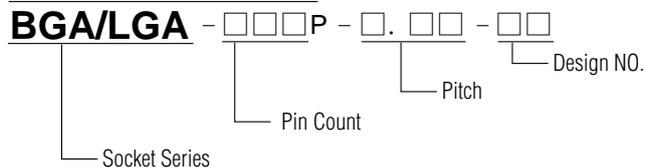
BGA/LGA

BALL/LAND GRID ARRAY



※RoHS compliant

ORDERING PROCEDURE



SPECIFICATIONS

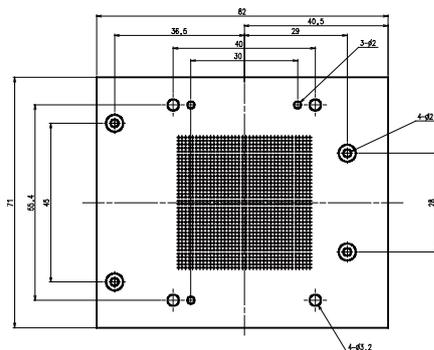
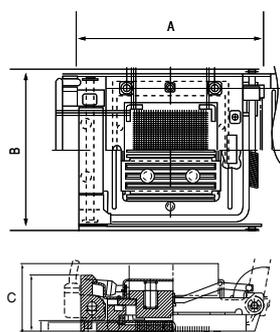
- Contact resistance: Initial 500mΩ (PS) / 200mΩ (BPS)(At 10 mA)INITIAL
- Maximum voltage: AC300V RMS (for 1 minute)
- Insulation resistance: 1,000 MΩ or higher (At DC 500V)
- Rated current: 0.5A
- Insertion: Min 10,000 times (mechanical)

MATERIAL

- Body: PEI, PES
- Contact: BeCu, Au plating (Ni-base)

APPLICABLE IC DIMENSIONS & SOCKET DIMENSIONS

1.0mm PITCH



PCB PATTERN

BGA-1444P SERIES (1.0mm PITCH)

PART NO.	APPLICABLE IC DIMENSIONS (REF.)					OUTSIDE DIMENSIONS (REF.)			REMARKS
	BODY SIZE	GRID	ROW/ARRAY	LEADS NUMBER	PITCH	A	B	C	
BGA-955(1444P)-1.0-01	33×33	31	Depopulated	955	1.0	71	82	29.4	
BGA-1156(1444P)-1.0-**	35×35	34	Fully Array	1156					
BGA-1444P-1.0-**	40×40	38	Fully Array	1444					

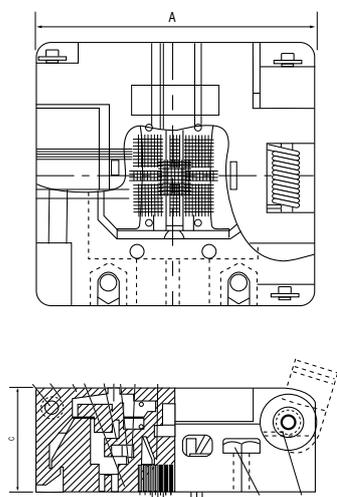
-Max.40×40mm Package can be accommodated

BGA-576P SERIES (0.65mm PITCH)

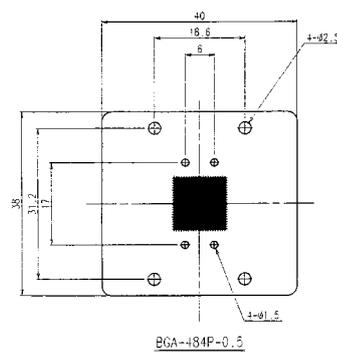
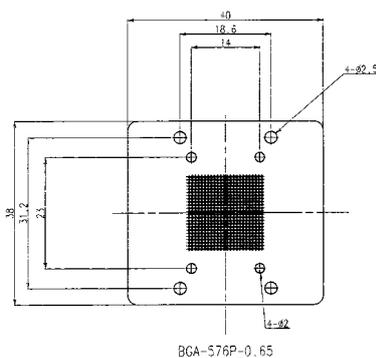
PART NO.	APPLICABLE IC DIMENSIONS (REF.)					OUTSIDE DIMENSIONS (REF.)			REMARKS
	BODY SIZE	GRID	ROW/ARRAY	LEADS NUMBER	PITCH	A	B	C	
BGA-100(576P)-0.65-16	7×7	10	Fully Array	100	0.65	40	38	15	
BGA-174(576P)-0.65-17	10×10	14	Depopulated	174					
BGA-204(576P)-0.65-10	12×12	18	Depopulated	204					
BGA-188(576P)-0.65-11	13×13	18	Depopulated	188					
BGA-232(576P)-0.65-04	14×14	20	Depopulated	232					
BGA-352(576P)-0.65-39	15×15	22	Depopulated	352					
BGA-324(576P)-0.65-07	16×16	22	Depopulated	324					
BGA-304(576P)-0.65-14	16×16	23	Depopulated	304					

-Max.16×16mm Package can be accommodated

Applicable IC/BGA • LGA Clam Shell Surface Mount Type Socket



PCB PATTERN

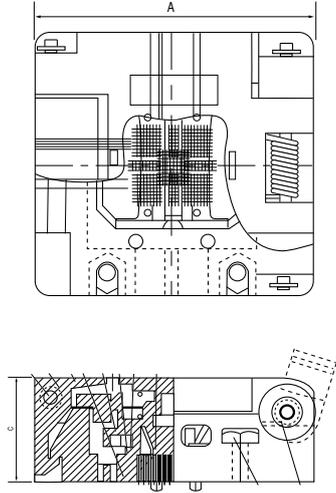


BGA-484P SERIES (0.5mm PITCH)

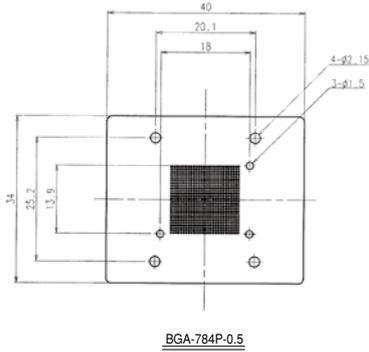
Unit : mm

PART NO.	APPLICABLE IC DIMENSIONS (REF.)				PITCH	OUTSIDE DIMENSIONS (REF.)			REMARKS
	BODY SIZE	GRID	ROW/ARRAY	LEADS NUMBER		A	B	C	
BGA-48(484P)-0.5-32	4×4	7	Depopulated	48	0.5	40	38	15	
BGA-48(484P)-0.5-01	5×5	8	Depopulated	48					
BGA-57(484P)-0.5-14	5×5	9	Depopulated	57					
BGA-89(484P)-0.5-11	6×6	10	Depopulated	89					
BGA-96(484P)-0.5-26	6×6	11	Depopulated	96					
BGA-144(484P)-0.5-07	7×7	12	Depopulated	144					
BGA-144(484P)-0.5-20	7×7	13	Depopulated	144					
BGA-132(484P)-0.5-36	8×8	14	Depopulated	132					
BGA-161(484P)-0.5-40	8×8	15	Depopulated	161					
BGA-156(484P)-0.5-19	9×9	17	Depopulated	156					
BGA-277(484P)-0.5-08	10×10	18	Depopulated	277					
BGA-240(484P)-0.5-10	10×10	19	Depopulated	240					
BGA-223(484P)-0.5-13	11×11	20	Depopulated	223					
BGA-256(484P)-0.5-44	11×11	21	Depopulated	256					
BGA-244(484P)-0.5-04	12×12	21	Depopulated	244					

-Max.12×12mm Package can be accommodated



PCB PATTERN



BGA-784P-0.5

BGA-784P SERIES (0.5mm PITCH)

Unit : mm

PART NO.	APPLICABLE IC DIMENSIONS (REF.)					OUTSIDE DIMENSIONS (REF.)			REMARKS
	BODY SIZE	GRID	ROW/ARRAY	LEADS NUMBER	PITCH	A	B	C	
BGA-64(784P)-0.5-30	5×5	8	Fully Array	64	0.5	40	34	20	
BGA-81(784P)-0.5-088	5×5	9	Fully Array	81					
BGA-73(784P)-0.5-55	6×6	9	Depopulated	73					
BGA-100(784P)-0.5-56	6×6	10	Fully Array	100					
BGA-128(784P)-0.5-19	7×7	12	Depopulated	128					
BGA-137(784P)-0.5-182	7×7	13	Depopulated	137					
BGA-132(784P)-0.5-50	8×8	14	Depopulated	132					
BGA-193(784P)-0.5-086	8×8	15	Depopulated	193					
BGA-255(784P)-0.5-093	9×9	16	Depopulated	255					
BGA-284(784P)-0.5-37	10×10	18	Depopulated	284					
BGA-361(784P)-0.5-091	10×10	19	Depopulated	361					
BGA-280(784P)-0.5-51	11×11	20	Depopulated	280					
BGA-328(784P)-0.5-74	11×11	21	Depopulated	328					
BGA-483(784P)-0.5-49	12×12	22	Depopulated	483					
BGA-433(784P)-0.5-68	12×12	23	Depopulated	433					
BGA-361(784P)-0.5-08	13×13	24	Depopulated	361					
BGA-517(784P)-0.5-63	13×13	25	Depopulated	517					
BGA-287(784P)-0.5-04	14×14	26	Depopulated	287					
BGA-440(784P)-0.5-*	14×14	27	Depopulated	440					
BGA-440(784P)-0.5-092	15×15	27	Depopulated	440					
BGA-385(784P)-0.5-06	15×15	28	Depopulated	385					
							38	15	

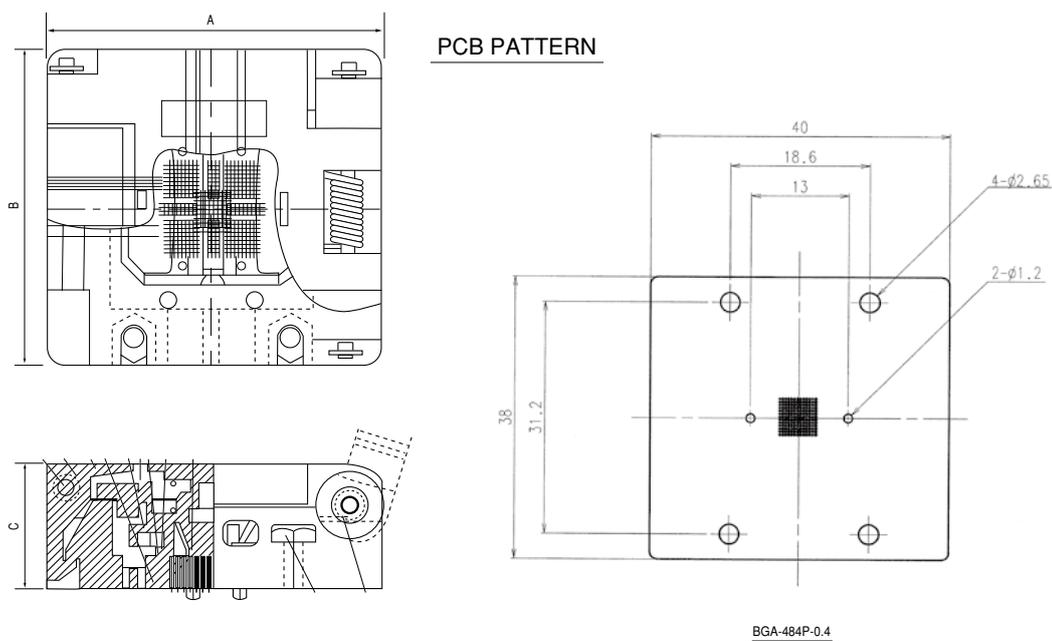
-Max.16×16mm Package can be accommodated

BGA-784BP SERIES (0.5mm PITCH) — Bypass Type —

Unit : mm

PART NO.	APPLICABLE IC DIMENSIONS (REF.)					OUTSIDE DIMENSIONS (REF.)			REMARKS
	BODY SIZE	GRID	ROW/ARRAY	LEADS NUMBER	PITCH	A	B	C	
BGA-121(784BP)-0.5-02	6×6	11×11	Fully Array	121	0.5	40	34	20.1	
BGA-344(784BP)-0.5-01	12×12	22×22	Depopulated	344					

Applicable IC/BGA·LGA Clam Shell Surface Mount Type Socket



BGA-484P SERIES (0.4mm PITCH)

Unit : mm

PART NO.	APPLICABLE IC DIMENSIONS (REF.)					OUTSIDE DIMENSIONS (REF.)			REMARKS
	BODY SIZE	GRID	ROW/ARRAY	LEADS NUMBER	PITCH	A	B	C	
BGA-132(484P)-0.4-039	6×6	12	Depopulated	132	0.4	40	34	20	
BGA-145(484P)-0.4-04	6×6	13	Depopulated	145					

-Max.10×10mm Package can be accommodated

BGA-484BP SERIES (0.4mm PITCH) — Bypass Type —

Unit : mm

PART NO.	APPLICABLE IC DIMENSIONS (REF.)					OUTSIDE DIMENSIONS (REF.)			REMARKS
	BODY SIZE	GRID	ROW/ARRAY	LEADS NUMBER	PITCH	A	B	C	
BGA-141(484BP)-0.4-**	6×6	13	Depopulated	141	0.4	40	34	19.9	